

IN THE ABSTRACT:

A frame-shaped groove is formed on a panel adhering part of a sealing board-(10), a paste including low melting point glass powder is buried in the groove, and a frame-shaped glass paste layer is formed. A solvent included in the glass paste layer is volatilized for solidification, and a low melting point glass frame-(22) is provided. Then, the low melting point glass frame (22) protruded on the surface of the sealing board-(10) is removed, and the surface of a plane including the surface of the adhering part of the sealing board-(10) is flattened. A low heat resistant layer-(24) is formed on the flattened adhering plane of the sealing board-(10). The sealing board-(10) is arranged to face an element board-(26) at a prescribed interval, laser beams are applied on the low melting point glass frame-(22) through the element board-(26), and the area is heated. Thus, the low melting point glass rises, and the sealing board-(10) is welded with the element board.